

Solder Joint Formation

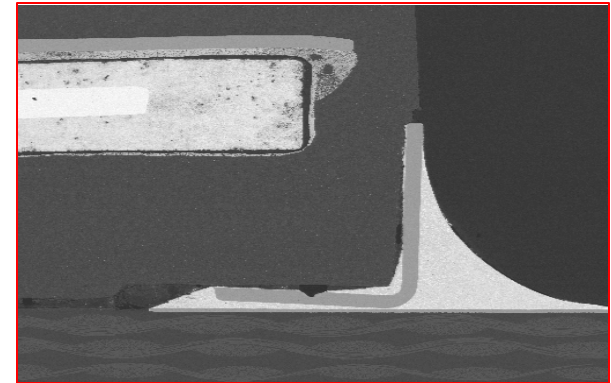
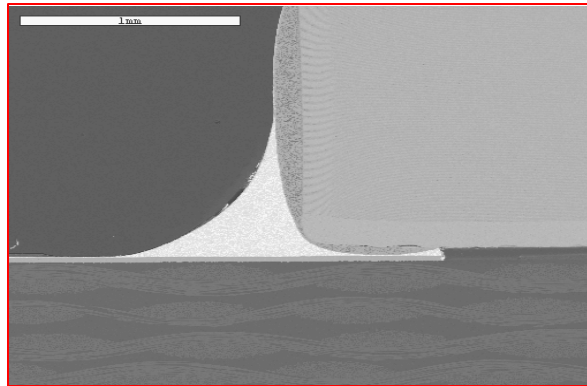
KEMET Products exhibit good joint formation in both lead bearing and lead-free soldering applications and meet JESD22-B102D criteria for dip & look (applies to SMD & TH) and process simulation test (applies to SMDs only).

Ceramic SMD

Tantalum MnO₂ SMD

Solder / Profile

SnPb



Pb-Free

